

# SOT622-1

plastic low profile fine-pitch ball grid array package; 180 balls; body 12 x 12 x 1.05 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA180
<b>Package type industry code</b>	LFPGA180
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-205
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	13-2-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A <sub>2</sub>	package height	0.95	-	1.05	1.2	mm
n <sub>2</sub>	actual quantity of termination	-	-	180	-	



## 2. Package outline

LFBGA180: plastic low profile fine-pitch ball grid array package; 180 balls; body 12 x 12 x 1.05 mm SOT622-1

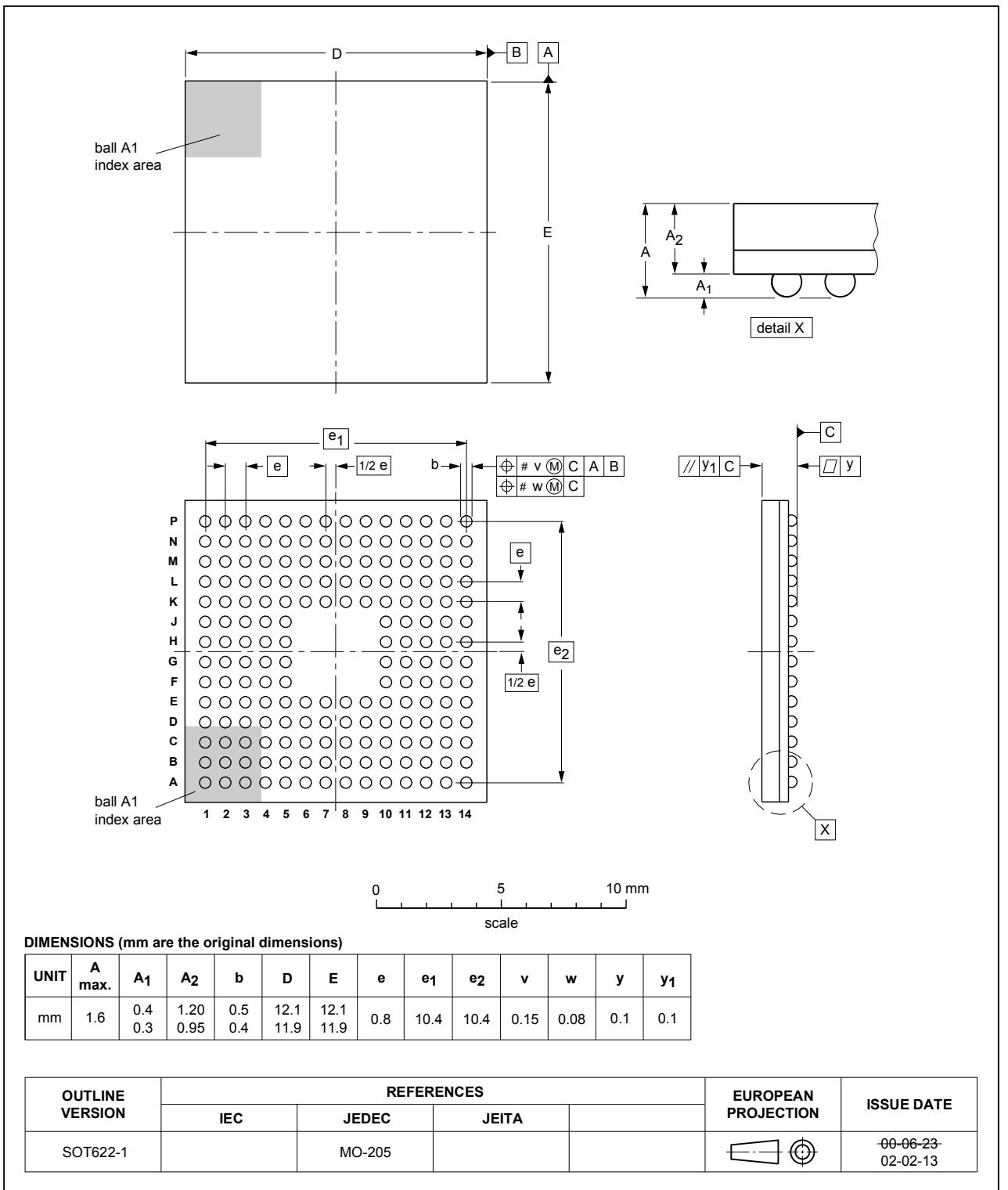


Fig. 1. Package outline LFBGA180 (SOT622-1)

### 3. Soldering

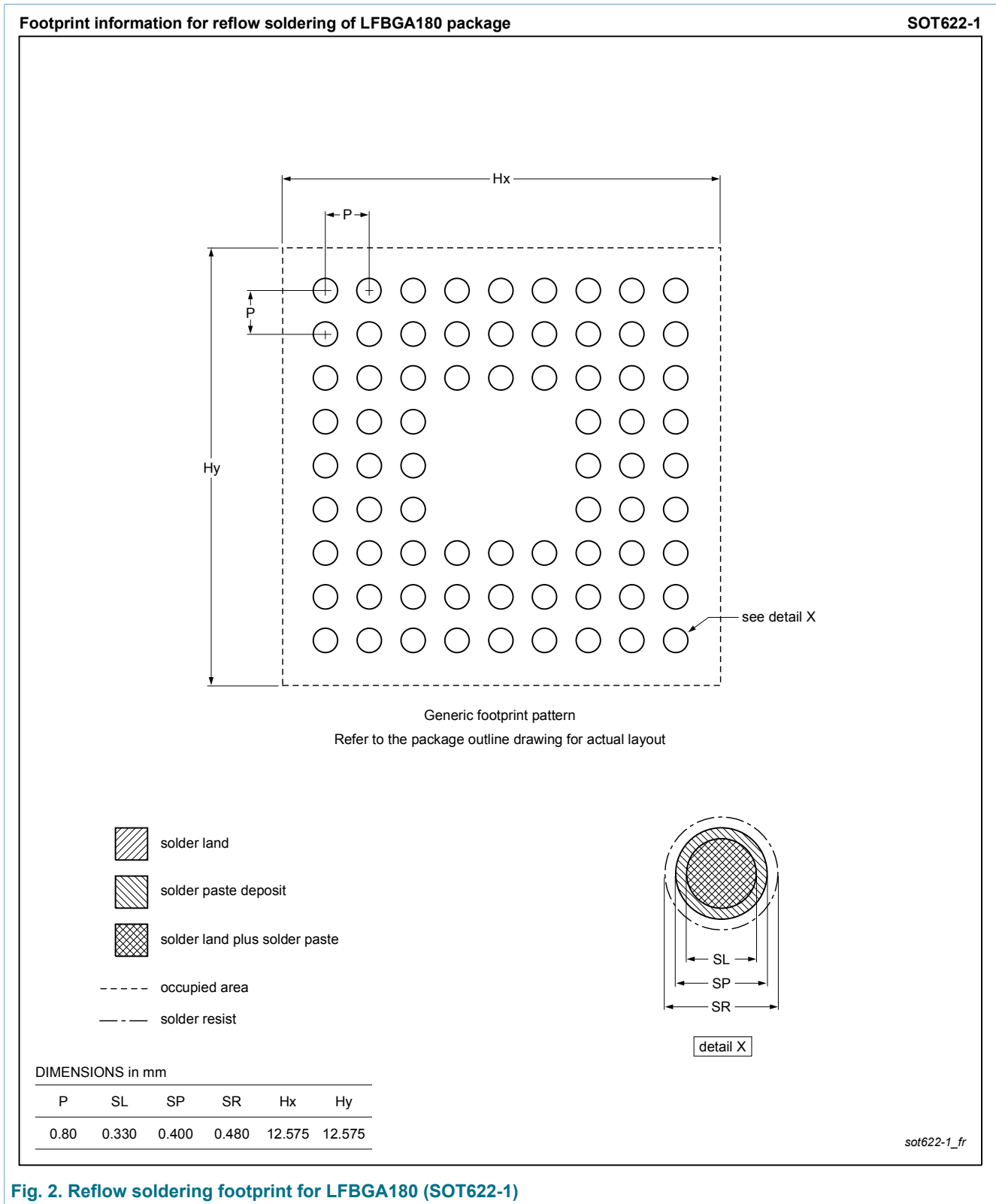


Fig. 2. Reflow soldering footprint for LFBGA180 (SOT622-1)

## 4. Legal information

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